

FQP20N06L

60V LOGIC N-Channel MOSFET

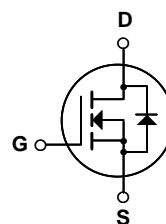
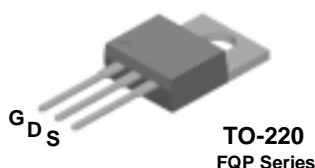
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- 21A, 60V, $R_{DS(on)} = 0.055\Omega$ @ $V_{GS} = 10V$
- Low gate charge (typical 9.5 nC)
- Low C_{rss} (typical 35 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	FQP20N06L	Units
V_{DSS}	Drain-Source Voltage	60	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$) - Continuous ($T_C = 100^\circ\text{C}$)	21	A
		14.7	A
I_{DM}	Drain Current - Pulsed (Note 1)	84	A
V_{GSS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	170	mJ
I_{AR}	Avalanche Current (Note 1)	21	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	5.3	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	7.0	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$) - Derate above 25°C	53	W
		0.35	W/°C
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	°C
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	Typ	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	--	2.85	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5	--	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	62.5	°C/W

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	60	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	--	0.06	--	V/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 48\text{ V}, T_C = 150^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	1.0	--	2.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 10.5\text{ A}$	--	0.042	0.055	Ω
		$V_{GS} = 5\text{ V}, I_D = 10.5\text{ A}$	--	0.055	0.07	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 25\text{ V}, I_D = 10.5\text{ A}$ (Note 4)	--	11	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	480	630	pF
C_{oss}	Output Capacitance		--	175	230	pF
C_{rss}	Reverse Transfer Capacitance		--	35	45	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30\text{ V}, I_D = 10.5\text{ A},$ $R_G = 25\text{ }\Omega$ (Note 4, 5)	--	10	30	ns
t_r	Turn-On Rise Time		--	165	340	ns
$t_{d(off)}$	Turn-Off Delay Time		--	35	80	ns
t_f	Turn-Off Fall Time		--	70	150	ns
Q_g	Total Gate Charge	$V_{DS} = 48\text{ V}, I_D = 21\text{ A},$ $V_{GS} = 5\text{ V}$ (Note 4, 5)	--	9.5	13	nC
Q_{gs}	Gate-Source Charge		--	2.5	--	nC
Q_{gd}	Gate-Drain Charge		--	5.5	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	21	A
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	84	A
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 21 A	--	--	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 21 A,	--	54	--	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs (Note 4)	--	75	--	nC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 450\text{ }\mu\text{H}$, $I_{AS} = 21\text{ A}$, $V_{DD} = 25\text{ V}$, $R_G = 25\text{ }\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 21\text{ A}$, $di/dt \leq 300\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\text{ }\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics

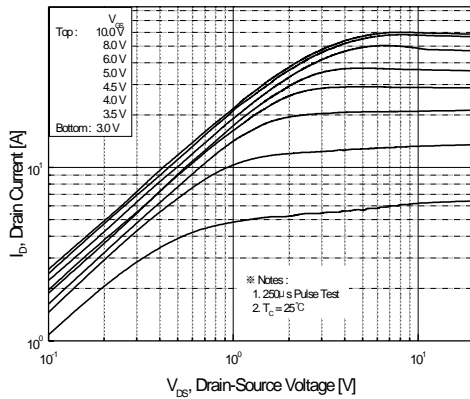


Figure 1. On-Region Characteristics

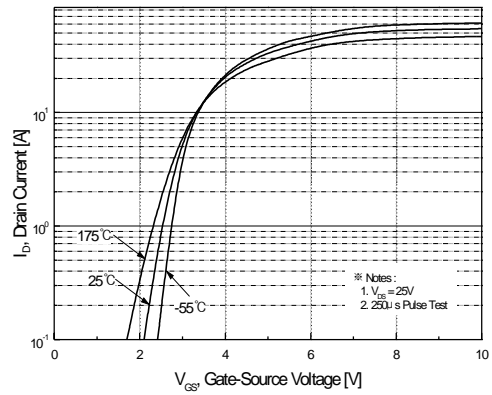


Figure 2. Transfer Characteristics

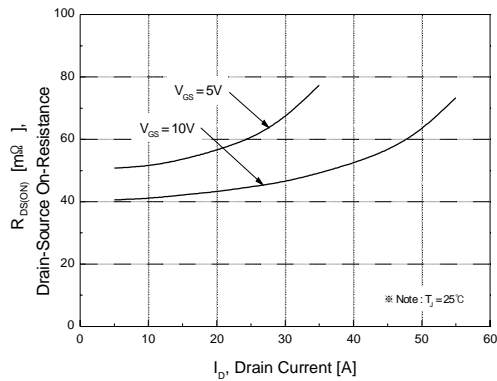


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

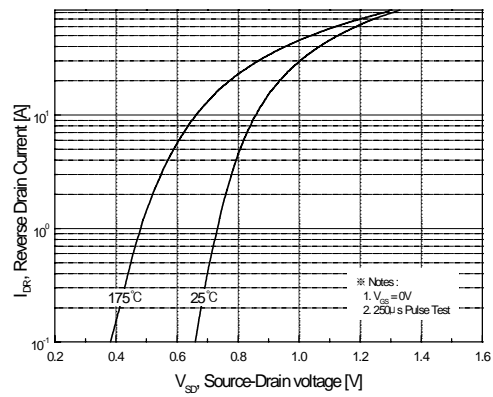


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

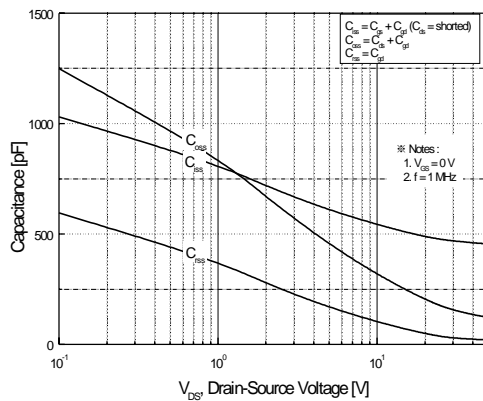


Figure 5. Capacitance Characteristics

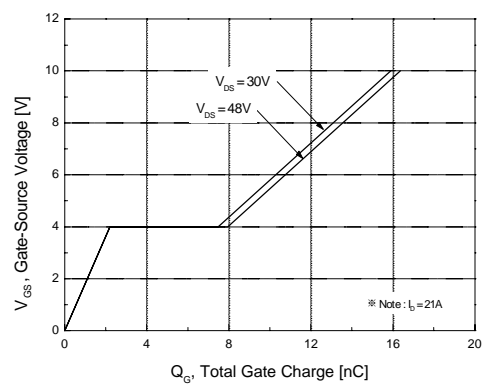


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

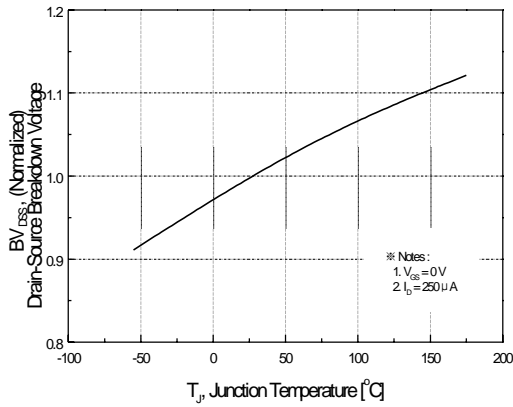


Figure 7. Breakdown Voltage Variation vs. Temperature

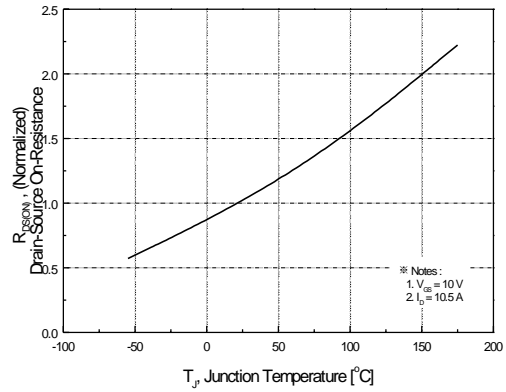


Figure 8. On-Resistance Variation vs. Temperature

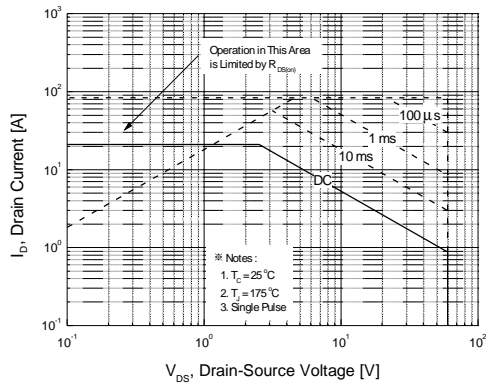


Figure 9. Maximum Safe Operating Area

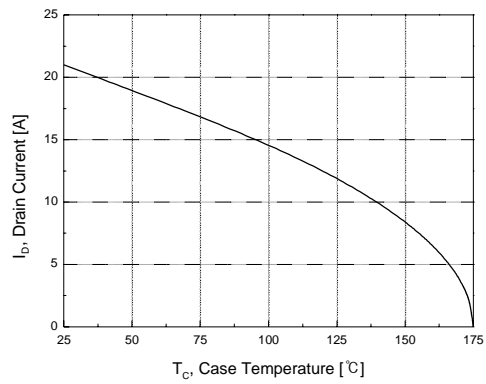


Figure 10. Maximum Drain Current vs. Case Temperature

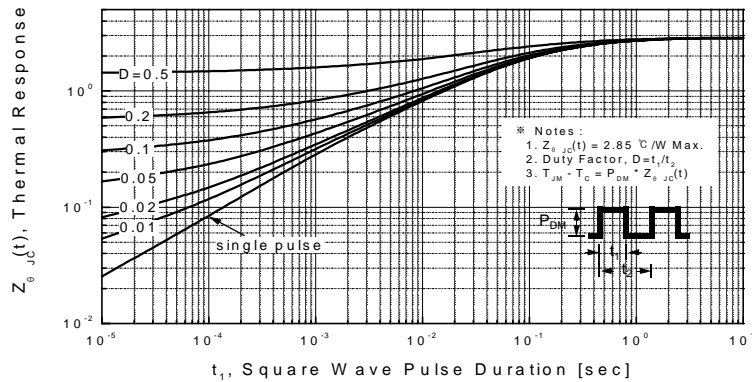
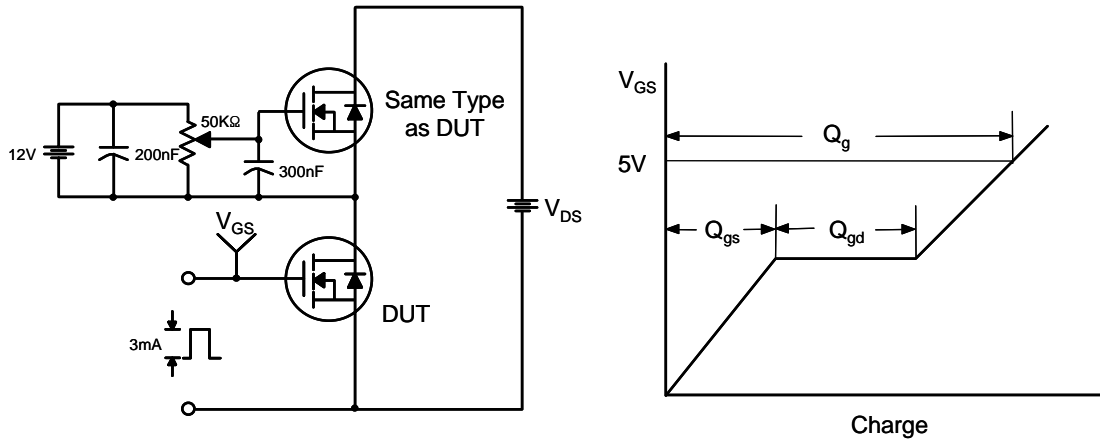
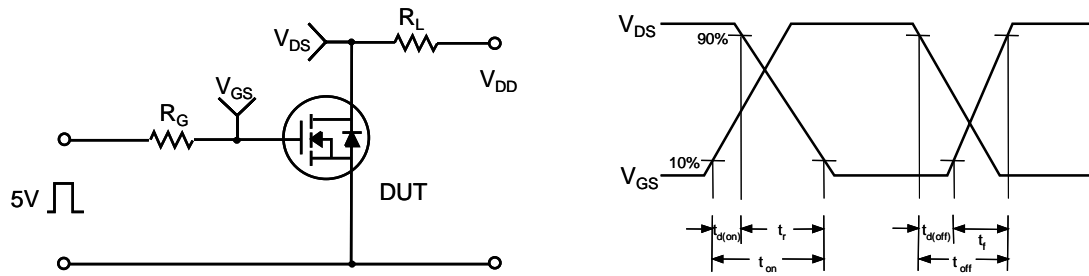


Figure 11. Transient Thermal Response Curve

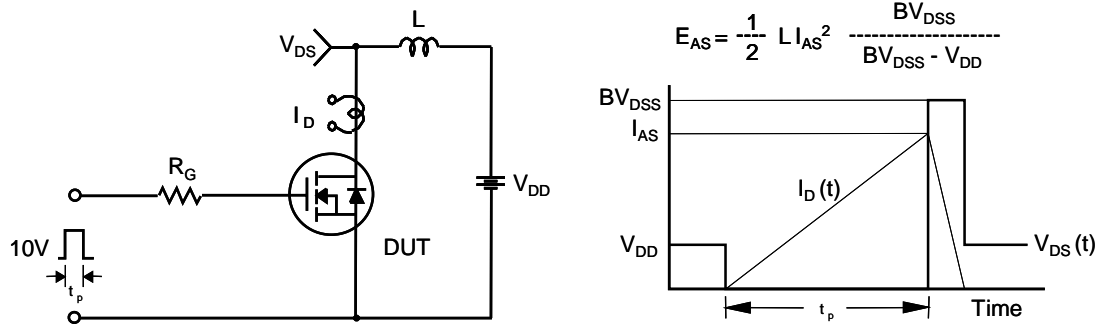
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms

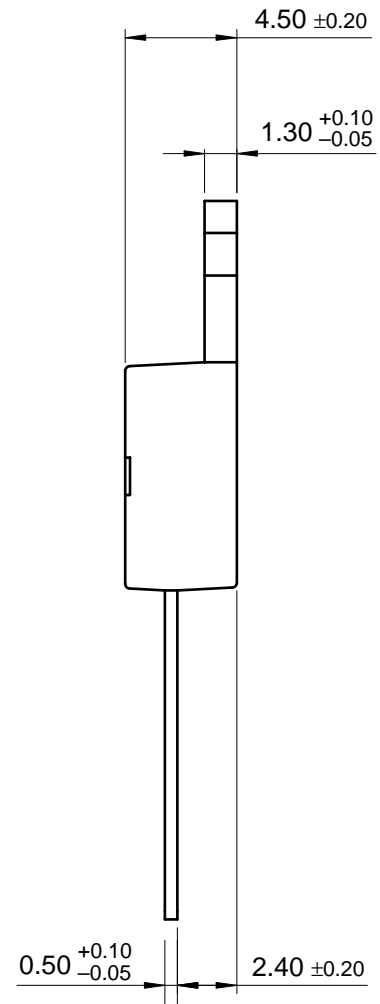
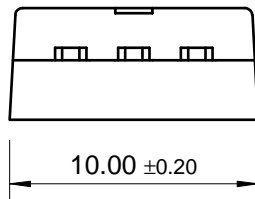


TO-220

Technical drawing of a 3-pin connector. The drawing shows a top view and a side view. The top view is a rectangle with a central circular hole. The side view shows three pins extending from the bottom. Dimensions are given in millimeters (mm) with tolerances.

Dimensions (mm):

- Overall width: 9.90 ± 0.20
- Width of central hole: (8.70)
- Radius of central hole: $\phi 3.60 \pm 0.10$
- Distance from top edge to center of hole: 1.30 ± 0.10
- Distance from top edge to bottom edge of central hole: 2.80 ± 0.10
- Distance from top edge to bottom edge of side holes: 15.90 ± 0.20
- Maximum distance from top edge to bottom edge of side holes: 18.95 MAX.
- Distance from top edge to bottom edge of side holes (left): (3.00)
- Distance from top edge to bottom edge of side holes (right): (3.70)
- Distance from top edge to bottom edge of side holes (left): (1.46)
- Distance from top edge to bottom edge of side holes (right): (1.00)
- Distance from top edge to bottom edge of side holes (left): 13.08 ± 0.20
- Distance from top edge to bottom edge of side holes (right): 10.08 ± 0.30
- Distance from top edge to bottom edge of side holes (left): 1.27 ± 0.10
- Distance from top edge to bottom edge of side holes (right): 1.52 ± 0.10
- Distance from top edge to bottom edge of side holes (left): 0.80 ± 0.10
- Distance from top edge to bottom edge of side holes (right): 0.80 ± 0.10
- Distance from top edge to bottom edge of side holes (left): 2.54 TYP
- Distance from top edge to bottom edge of side holes (right): 2.54 TYP
- Distance from top edge to bottom edge of side holes (left): $[2.54 \pm 0.20]$
- Distance from top edge to bottom edge of side holes (right): $[2.54 \pm 0.20]$



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